

FIG. 1

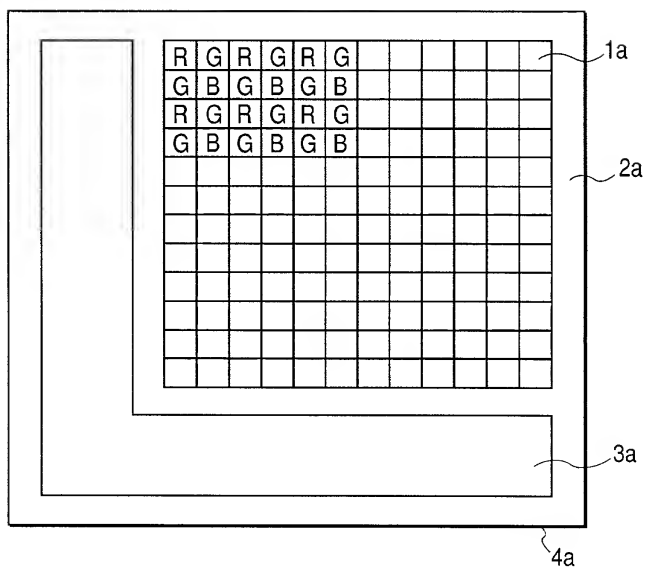


FIG. 2

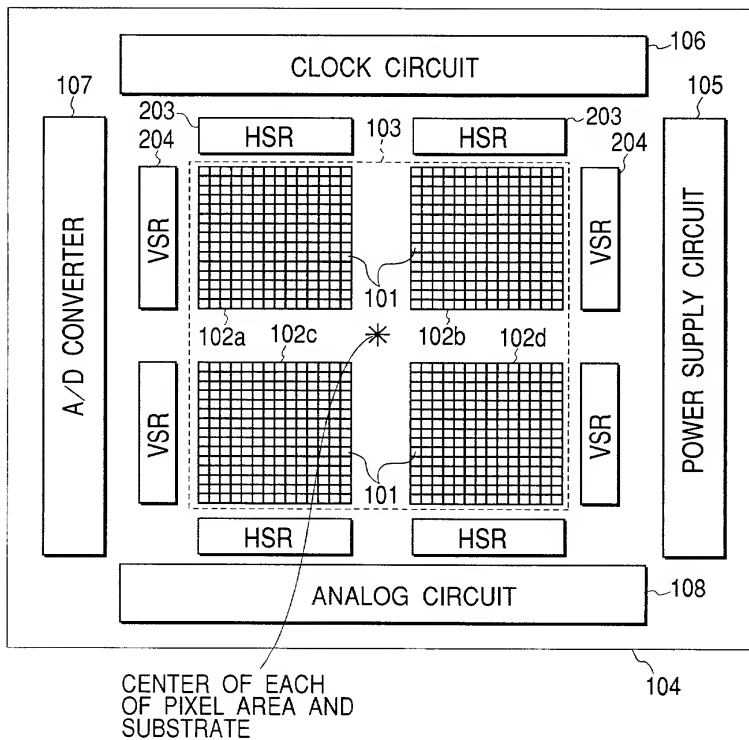


FIG. 3A

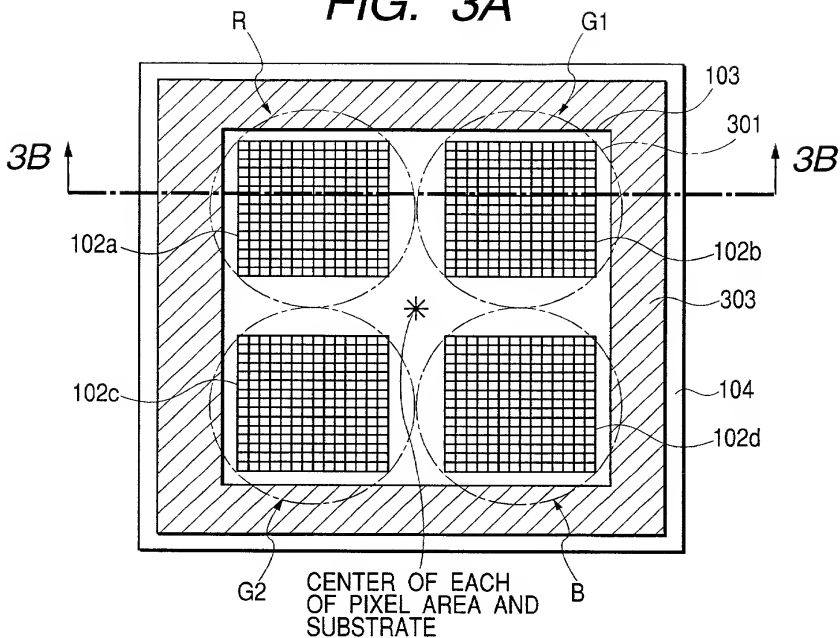


FIG. 3B

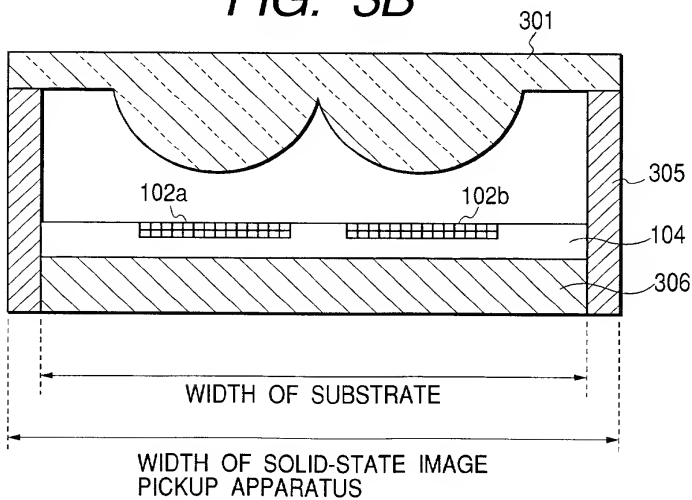


FIG. 4

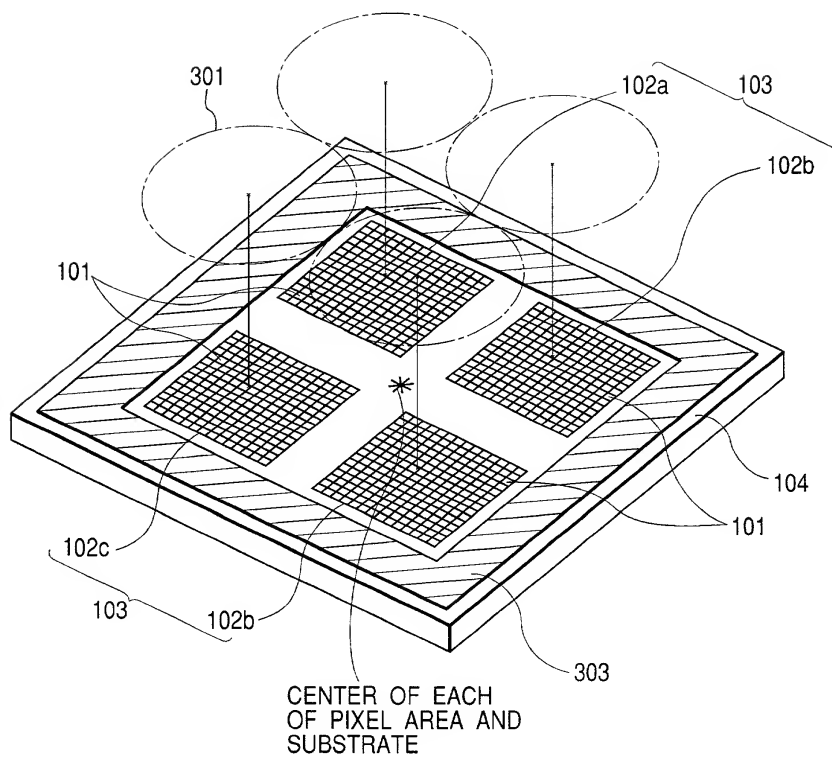
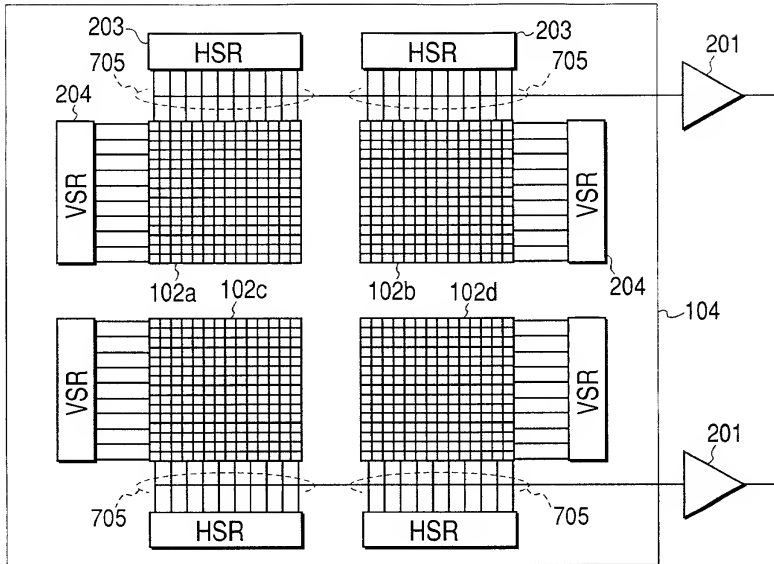
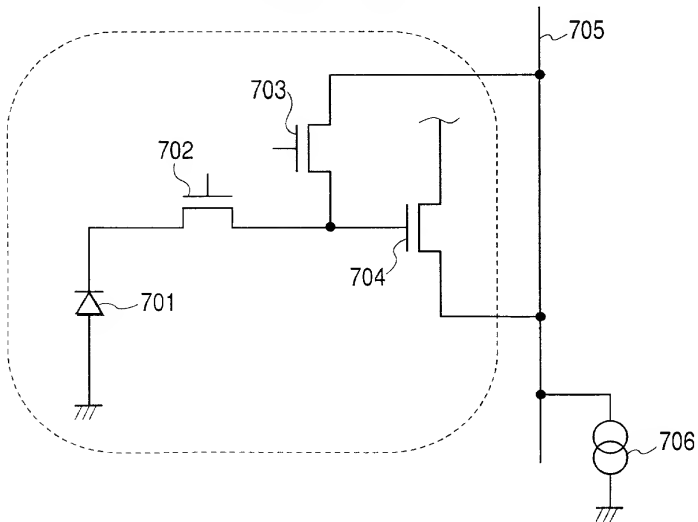


FIG. 5**FIG. 6**

[illegible]

FIG. 12 is a cross-sectional view of a solid-state image pickup apparatus. The apparatus consists of a substrate 301. On the top surface of the substrate, there is a central region 104. Within this region, there are two photoresist regions 102a and 102b. A protective layer 306 is located on the bottom surface of the substrate. The top surface of the substrate is labeled 305. The width of the substrate is indicated by a dimension line, and the width of the solid-state image pickup apparatus is also indicated by a dimension line.

FIG. 8

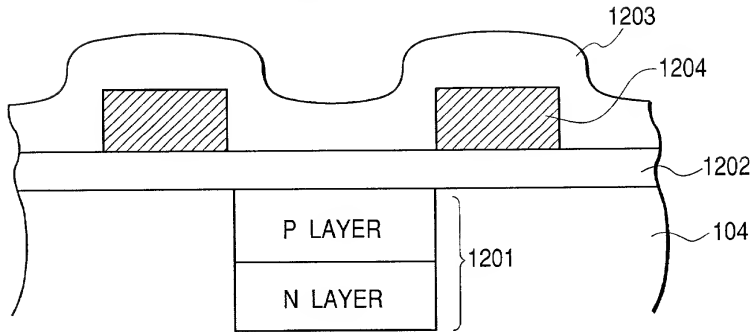


FIG. 9A

BEFORE CMP

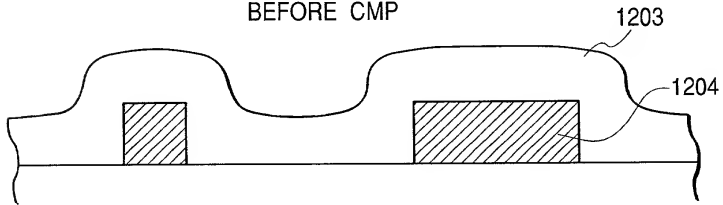


FIG. 9B

AFTER CMP

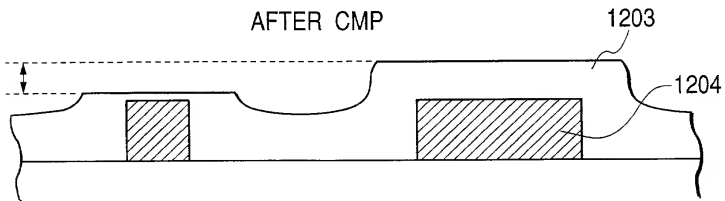


FIG. 10A

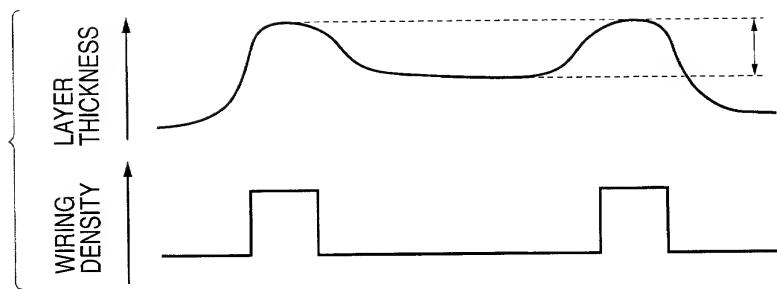


FIG. 10B

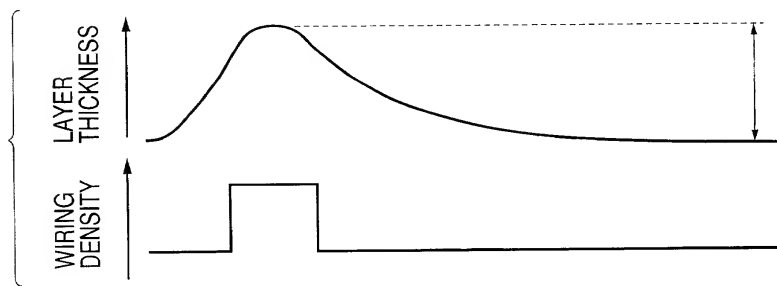


FIG. 11

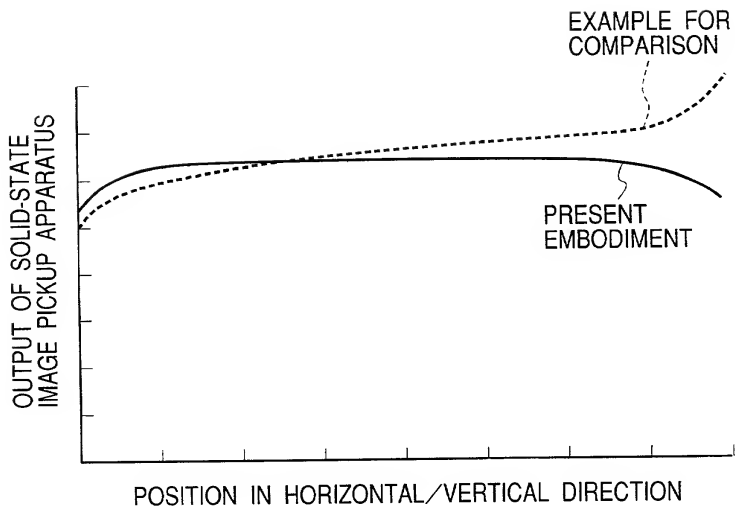


FIG. 12

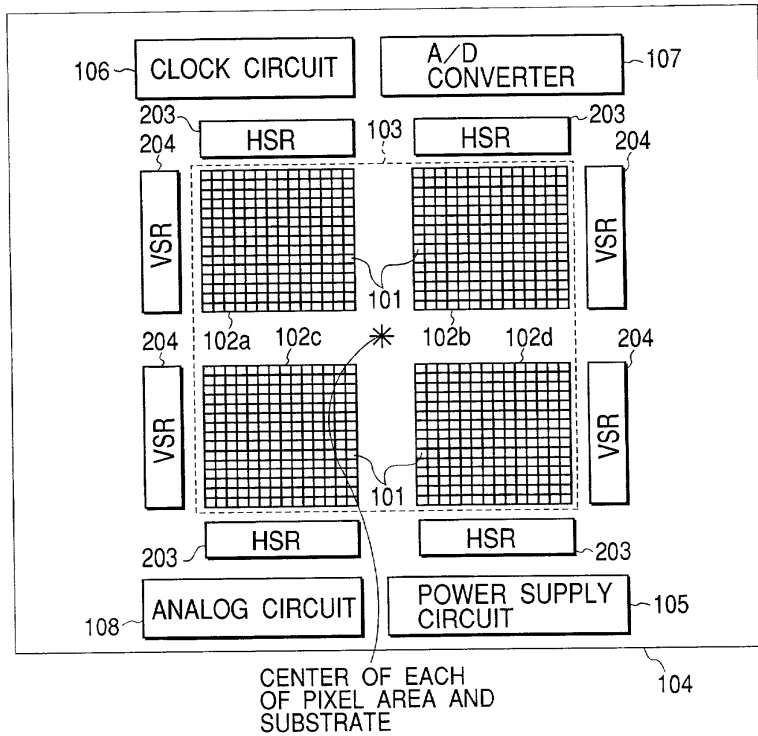


FIG. 13

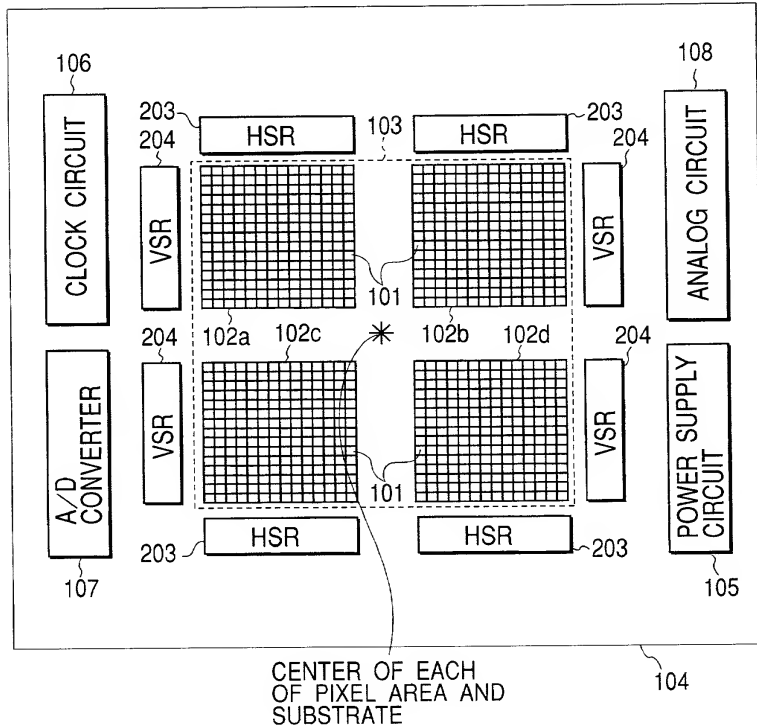


FIG. 14

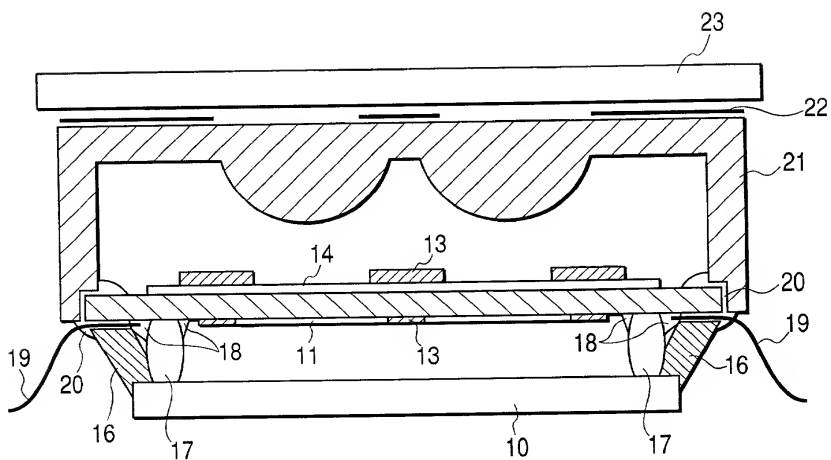


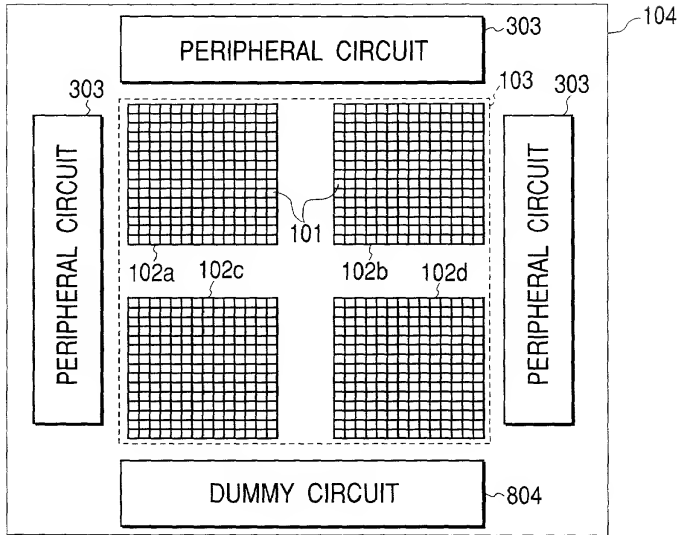
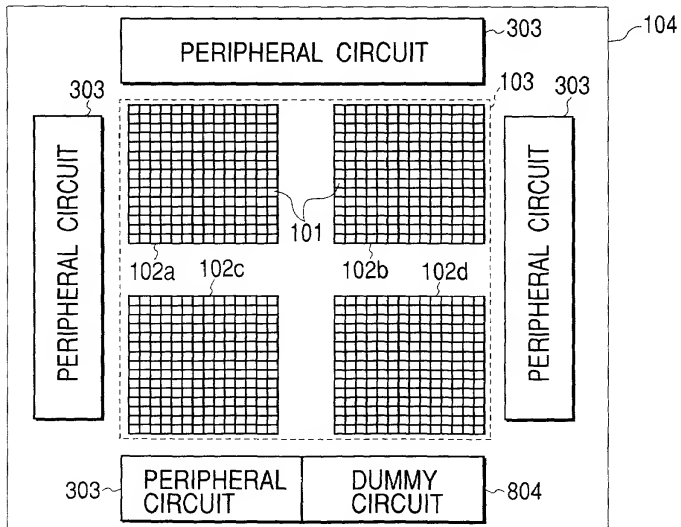
FIG. 15A**FIG. 15B**

FIG. 16

